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Form **PTO-1595** (Rev. 03-09) OMB No. 0651-0027 (exp. 03/31/2009)

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RECORDATION FORM COVER SH **PATENTS ONLY**

10-15-2009



103577258

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Eric Ka Wai Cheng, Xiangdang Xue	Internal Address:
Additional name(s) of conveying party(ies) attached? Yes No. 3. Nature of conveyance/Execution Date(s): Execution Date(s)02/19/2009 Assignment Merger Security Agreement Change of Name	Street Address: City: Hung Hom, Kowloon
Joint Research Agreement	State:
Government Interest Assignment Executive Order 9424, Confirmatory License	Country: Hong Kong Zip:
Other	Additional name(s) & address(es) attached? Yes X No
4. Application or patent number(s): A. Patent Application No.(s)	document is being filed together with a new application. B. Patent No.(s)
12/379,394	
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Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to: Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

PATENT

REEL: 023377 FRAME: 0895

Privacy Act Statement for Patent Assignment Recordation Form Cover Sheet

The Privacy Act of 1974 (P.L. 93-579) requires that you be given certain information in connection with the above request for information. This collection of information is authorized by 35 U.S.C. 1, 2, 261 and E.O. 9424. This information will primarily be used by the USPTO for the recordation of assignments related to patents and patent applications. Submission of this information is voluntary but is required in order for the USPTO to record the requested assignment. If you do not provide the information required on the cover sheet, the assignment will not be recorded, and all documents will be returned to you.

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PATENT REEL: 023377 FRAME: 0896

ASSIGNMENT

In consideration of One Dollar and other good and valuable consideration, of which receipt is acknowledged, I ____ Eric Ka Wai CHENG of The Hong Kong Polytechnic University, sell and assign to The Hong Kong Polytechnic University, a Hong Kong entity, the entire right, title, and interest in and to the invention titled Energy-Saving Controller for Three-Phase ... (IP-446A) invented by me as described in the application for United States patent executed by me concurrently herewith, and any and all applications for patent and patents in any and all countries, including all divisions, continuations, reissues, and extensions thereof and all rights of priority resulting from the filing of said United States application and authorize and request any official whose duty it is to issue patents to issue any patent on said improvements or resulting therefrom to said The Hong Kong Polytechnic University, or its successors, assigns, or nominees and agree that on request and without further consideration, but at the expense of The Hong Kong Polytechnic University, I will communicate to the University or its representatives or nominees any facts known to me respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing, and reissue applications, make all rightful oaths and generally aid said University, its successors, assigns, and nominees to obtain and enforce proper patent protection for said invention in all countries.

PATENT

REEL: 023377 FRAME: 0897

ASSIGNMENT

In consideration of One Dollar and other good and valuable consideration, of which receipt is acknowledged, I Xiangdang XUE of The Hong Kong Polytechnic University, sell and assign to The Hong Kong Polytechnic University, a Hong Kong entity, the entire right, title, and interest in and to the invention titled Energy-Saving Controller for Three-Phase ... (IP-446A) invented by me as described in the application for United States patent executed by me concurrently herewith, and any and all applications for patent and patents in any and all countries, including all divisions, continuations, reissues, and extensions thereof and all rights of priority resulting from the filing of said United States application and authorize and request any official whose duty it is to issue patents to issue any patent on said improvements or resulting therefrom to said The Hong Kong Polytechnic University, or its successors, assigns, or nominees and agree that on request and without further consideration, but at the expense of The Hong Kong Polytechnic University, I will communicate to the University or its representatives or nominees any facts known to me respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing, and reissue applications, make all rightful oaths and generally aid said University, its successors, assigns, and nominees to obtain and enforce proper patent protection for said invention in all countries.

, this 19 day of Feb 2009

PATENT
RECORDED: 10/09/2009 REEL: 023377 FRAME: 0898